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Yatago et al.

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(54) **SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE**

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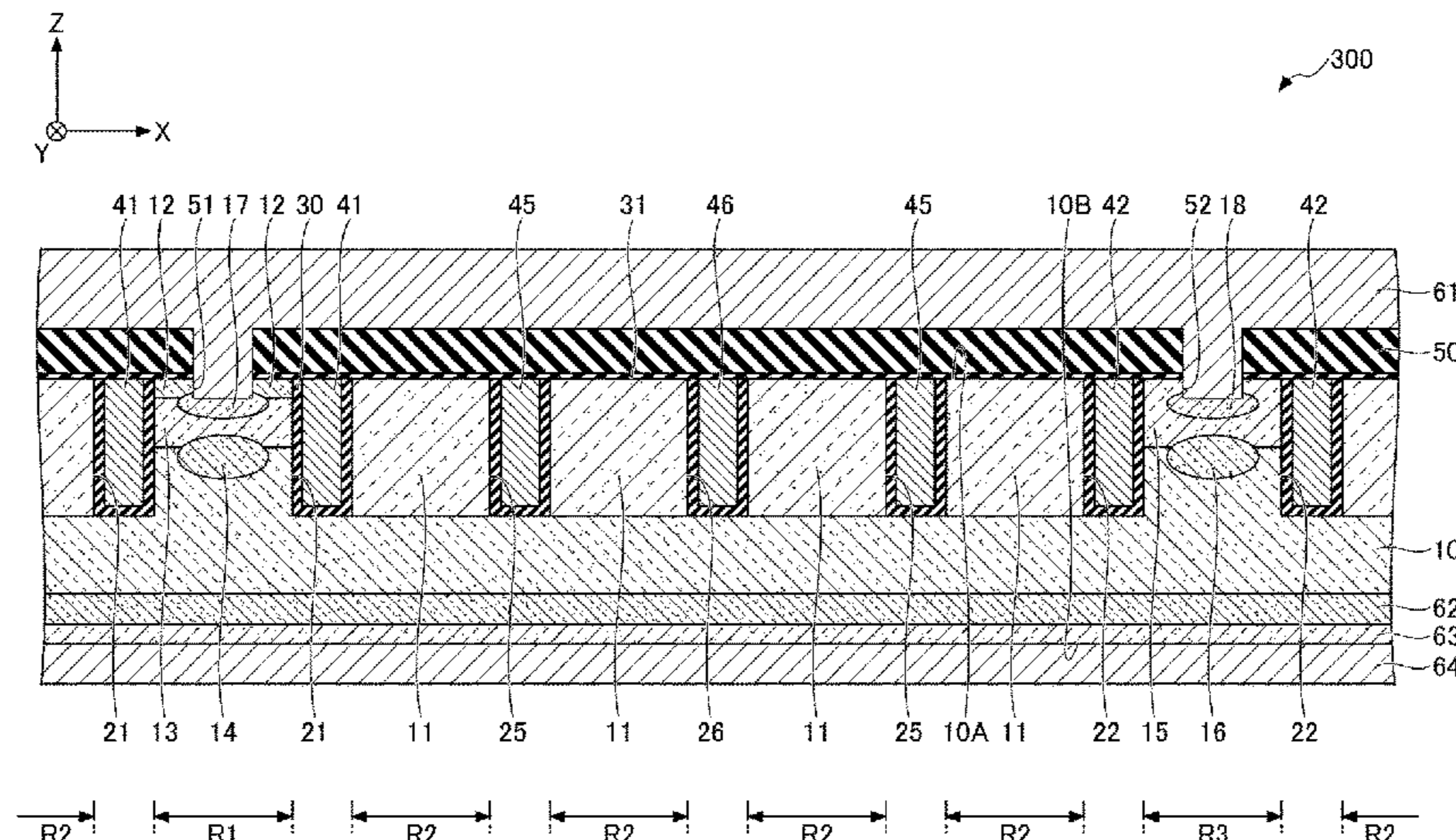
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(57) **ABSTRACT**

A semiconductor device includes first and second trenches, and a first layer provided therebetween, in a principal surface of a semiconductor substrate, a second layer in contact with and sandwiching the first trench with the first layer, a third layer provided under the second layer and in contact with the second layer and the first trench, a fourth layer provided under and in contact with the third layer but separated from the first trench, and a fifth layer provided in the principal surface and sandwiching the second trench with the first layer. The second and fourth layers are semiconductors of a first conductivity type, and the first, third, and fifth layers are semiconductors of a second conductivity type. A gate trench electrode is provided inside the first trench via the insulating film, and an emitter trench electrode is provided inside the second trench via the insulating film.

14 Claims, 17 Drawing Sheets



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H01L 29/40 (2006.01)
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See application file for complete search history.

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FIG.1

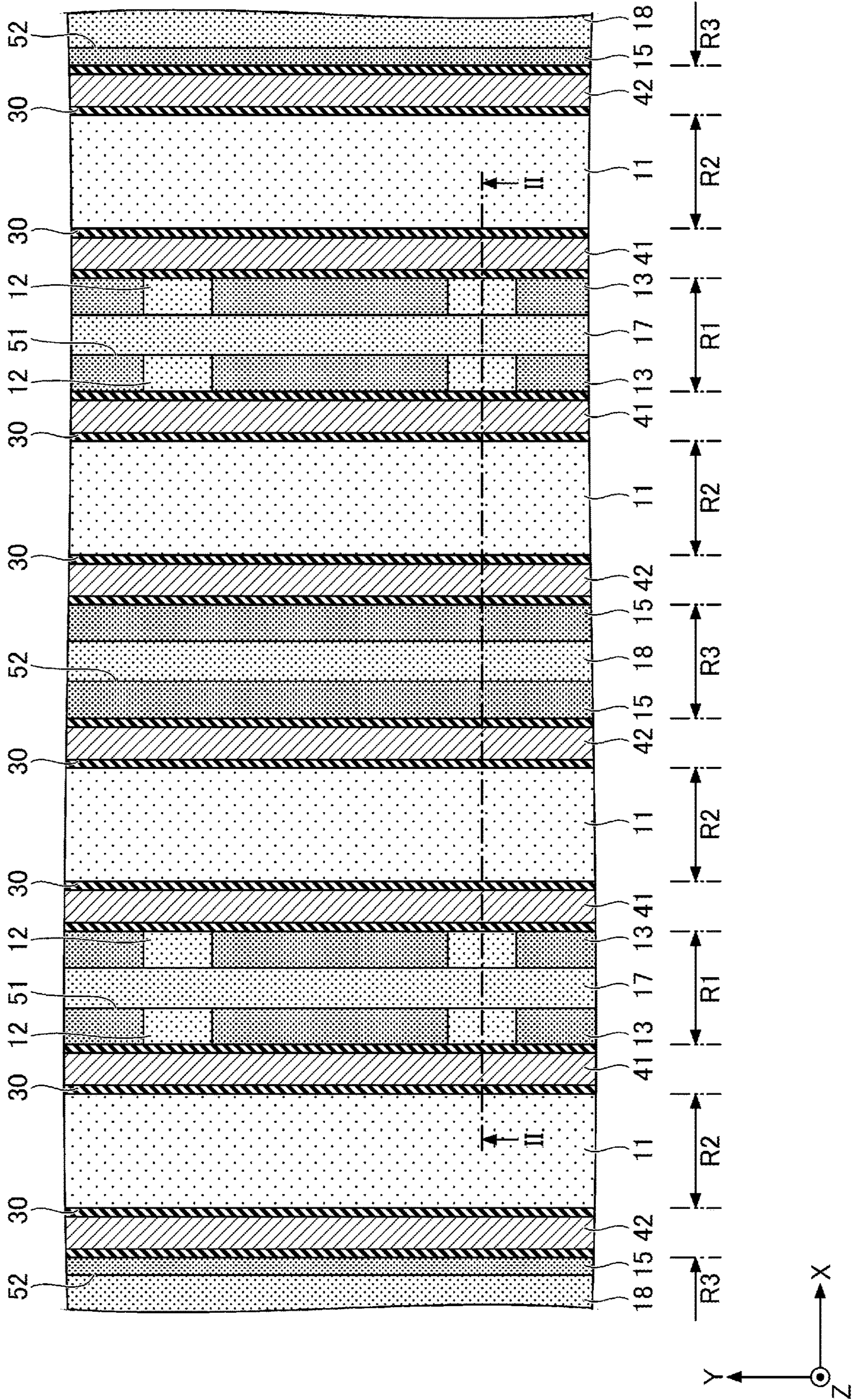


FIG. 2

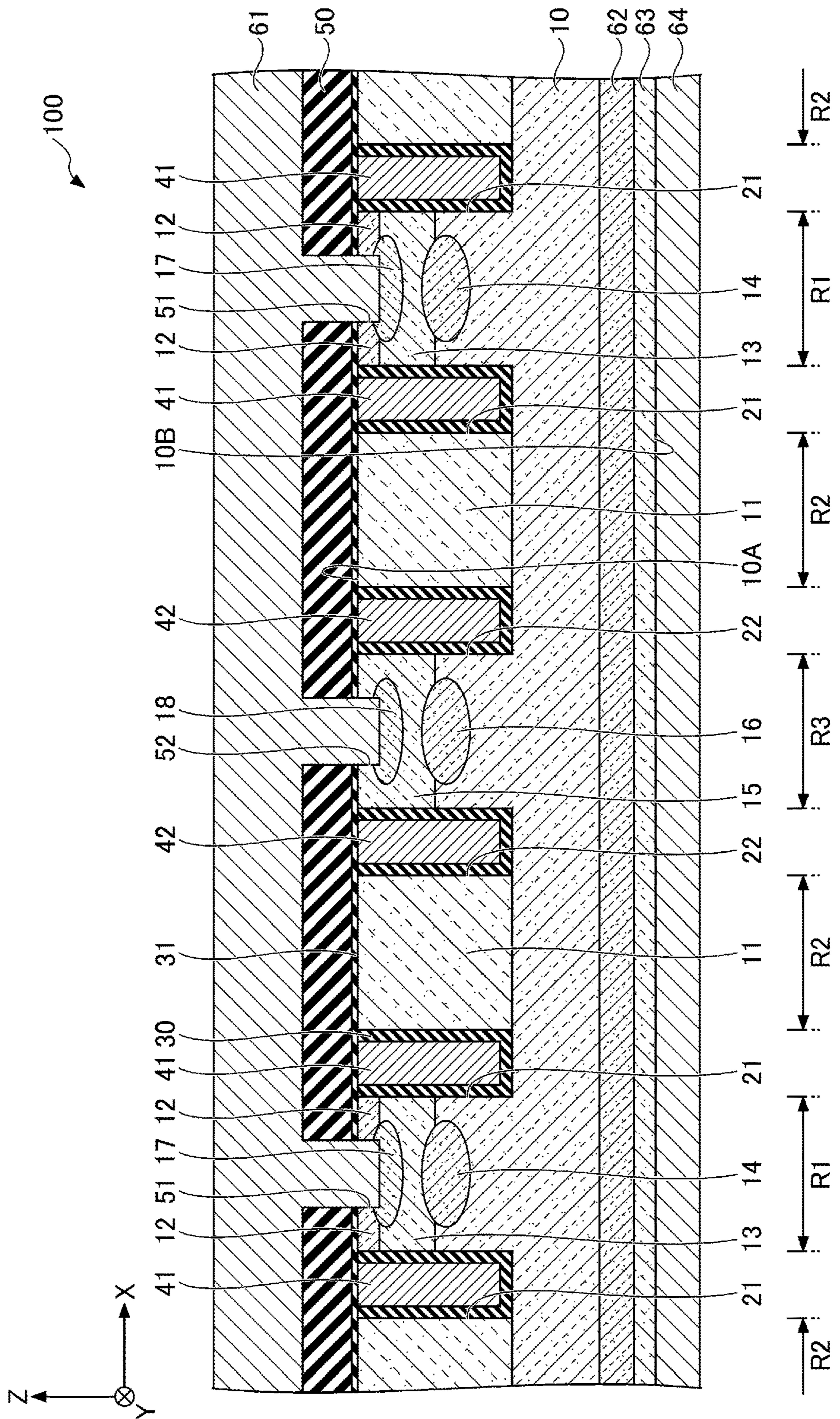


FIG.3

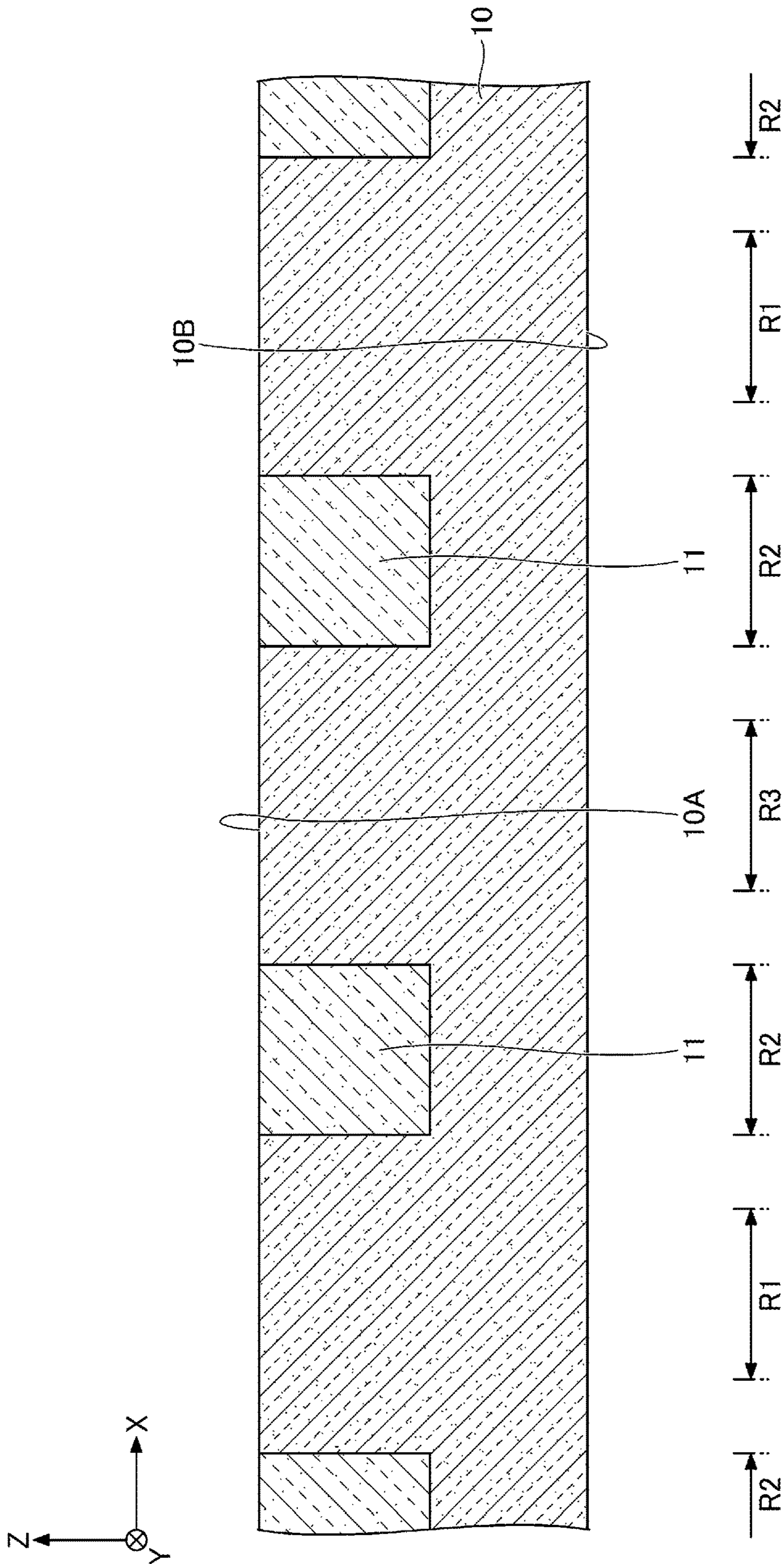


FIG.4

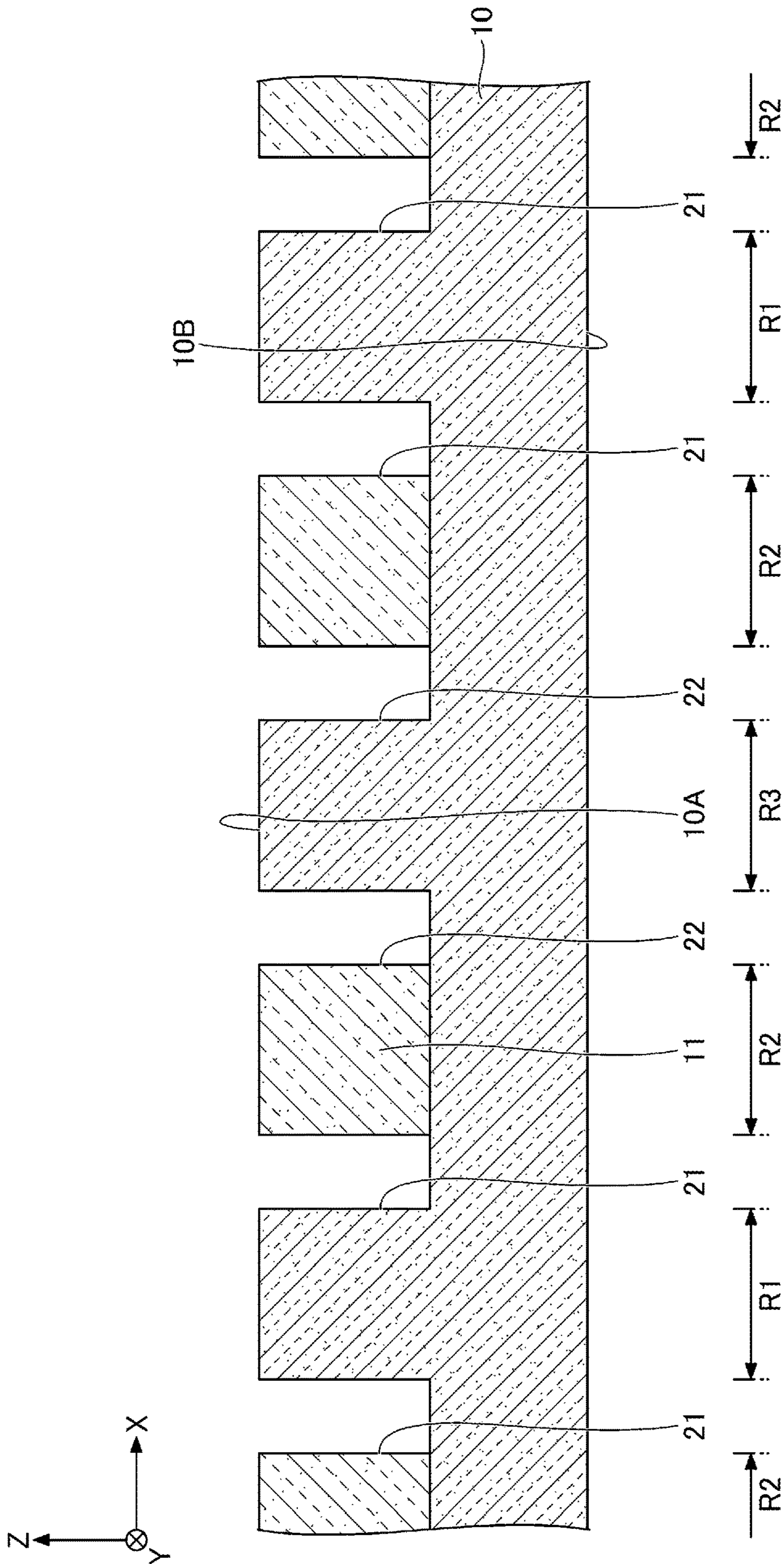


FIG. 5

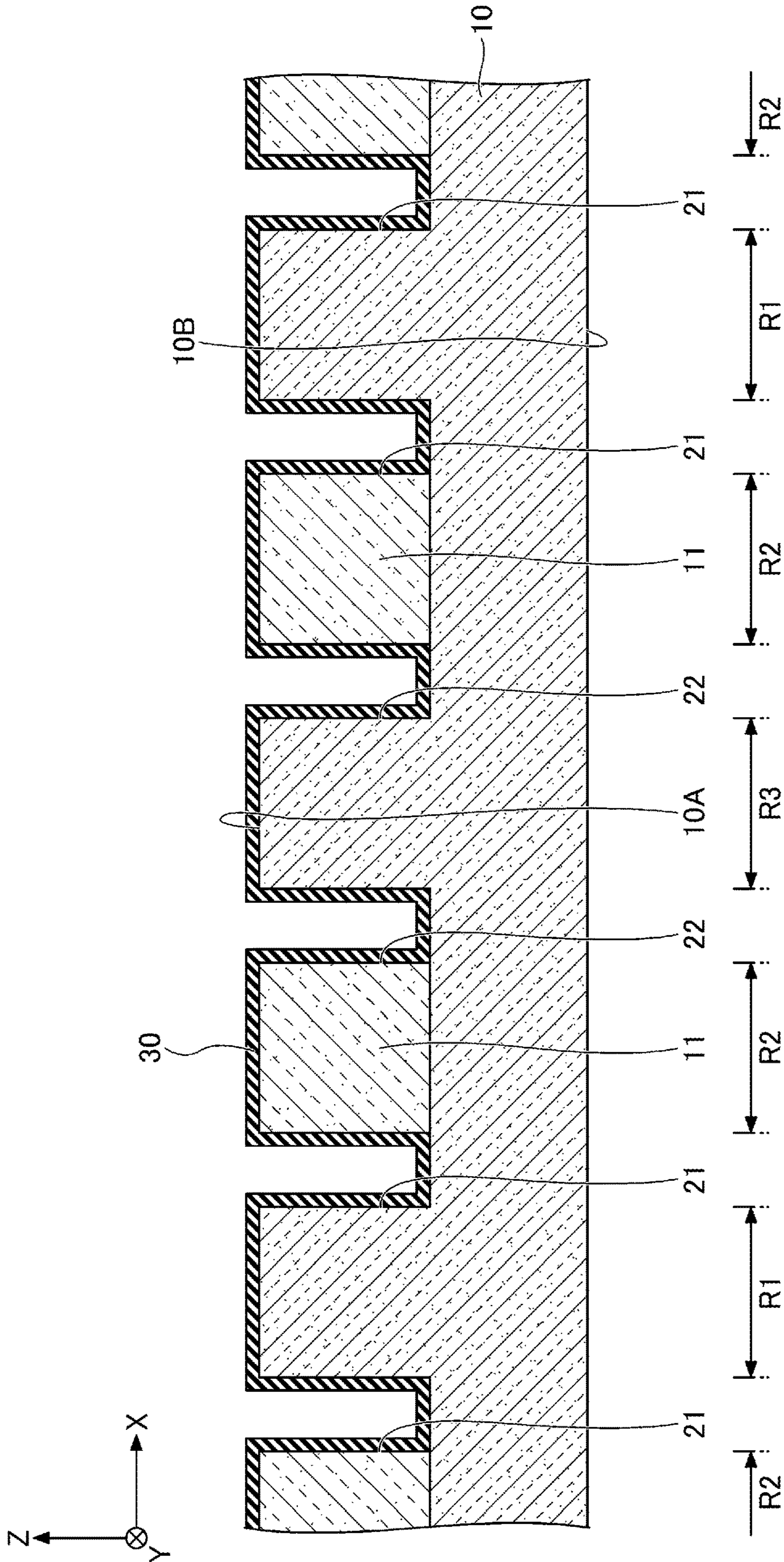


FIG. 6

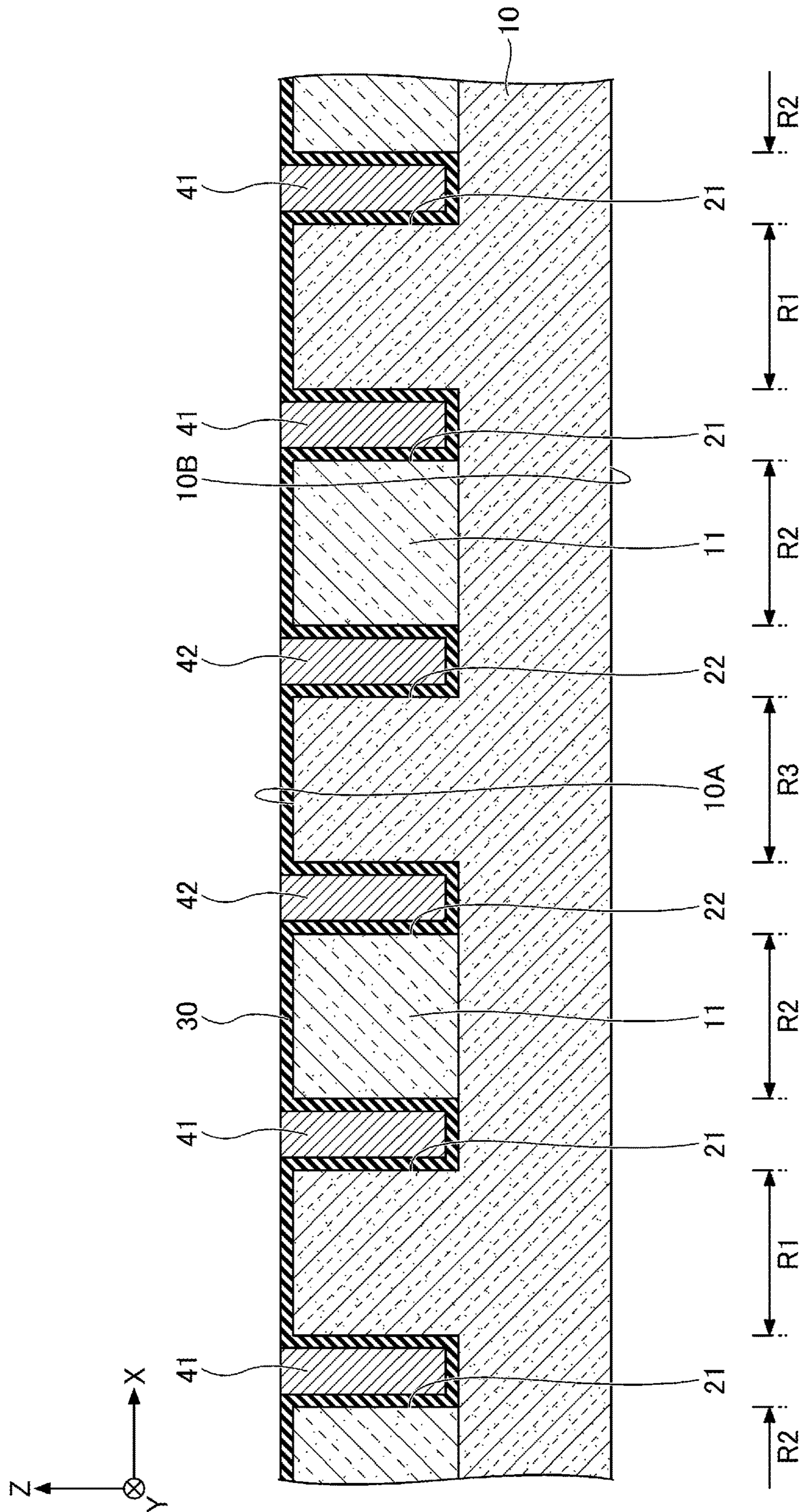


FIG. 7

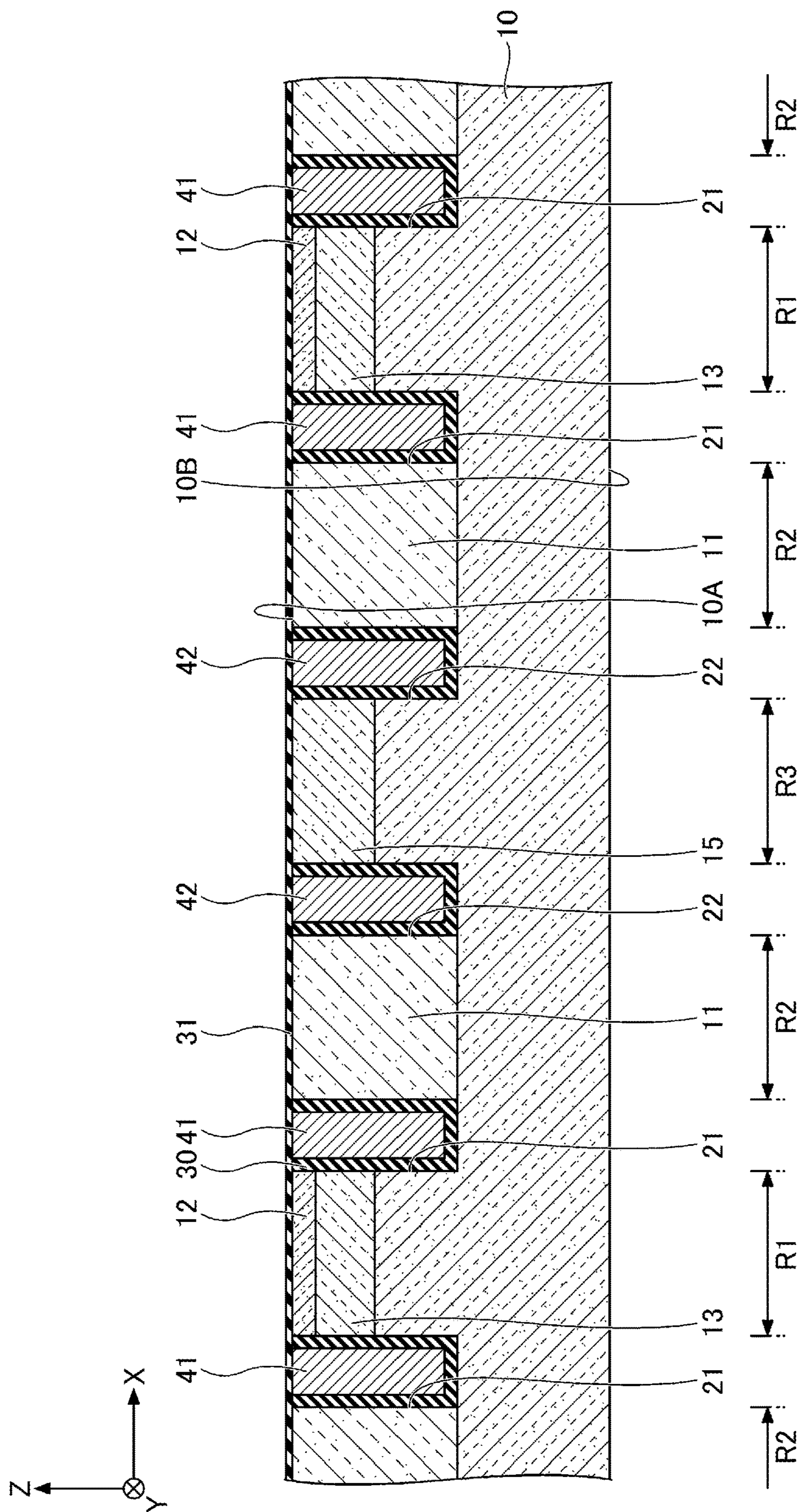


FIG.8

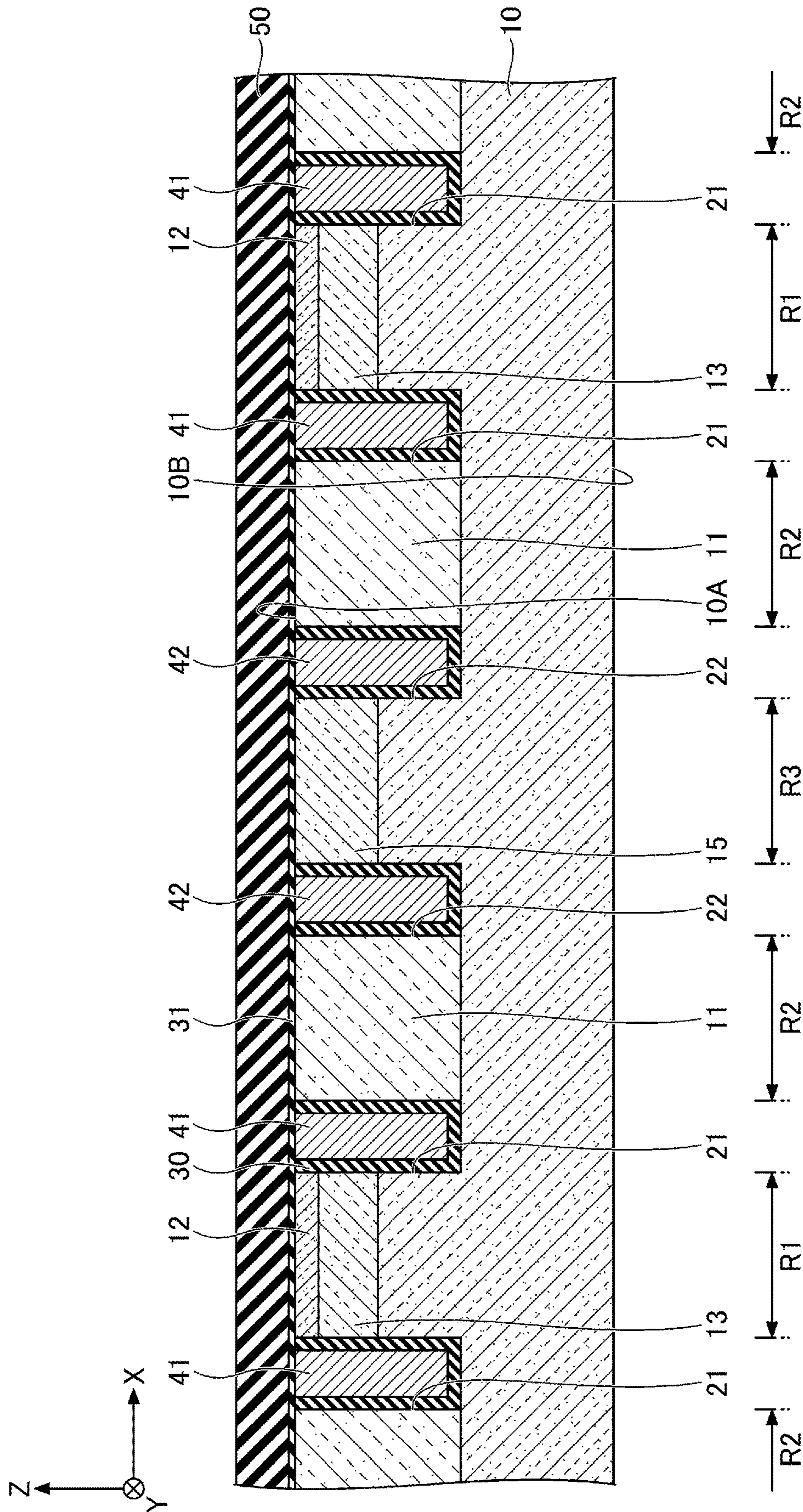


FIG.9

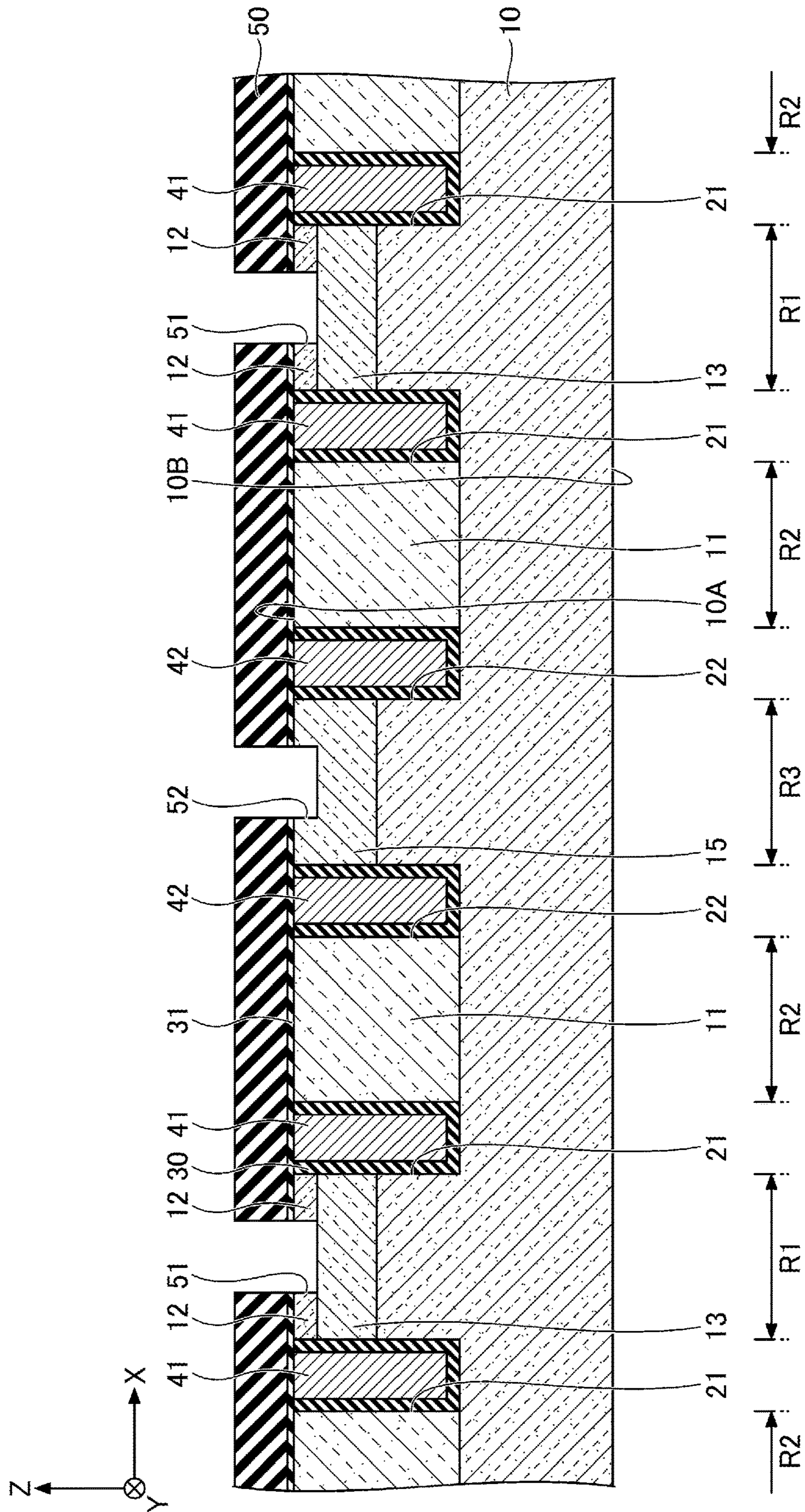


FIG.10

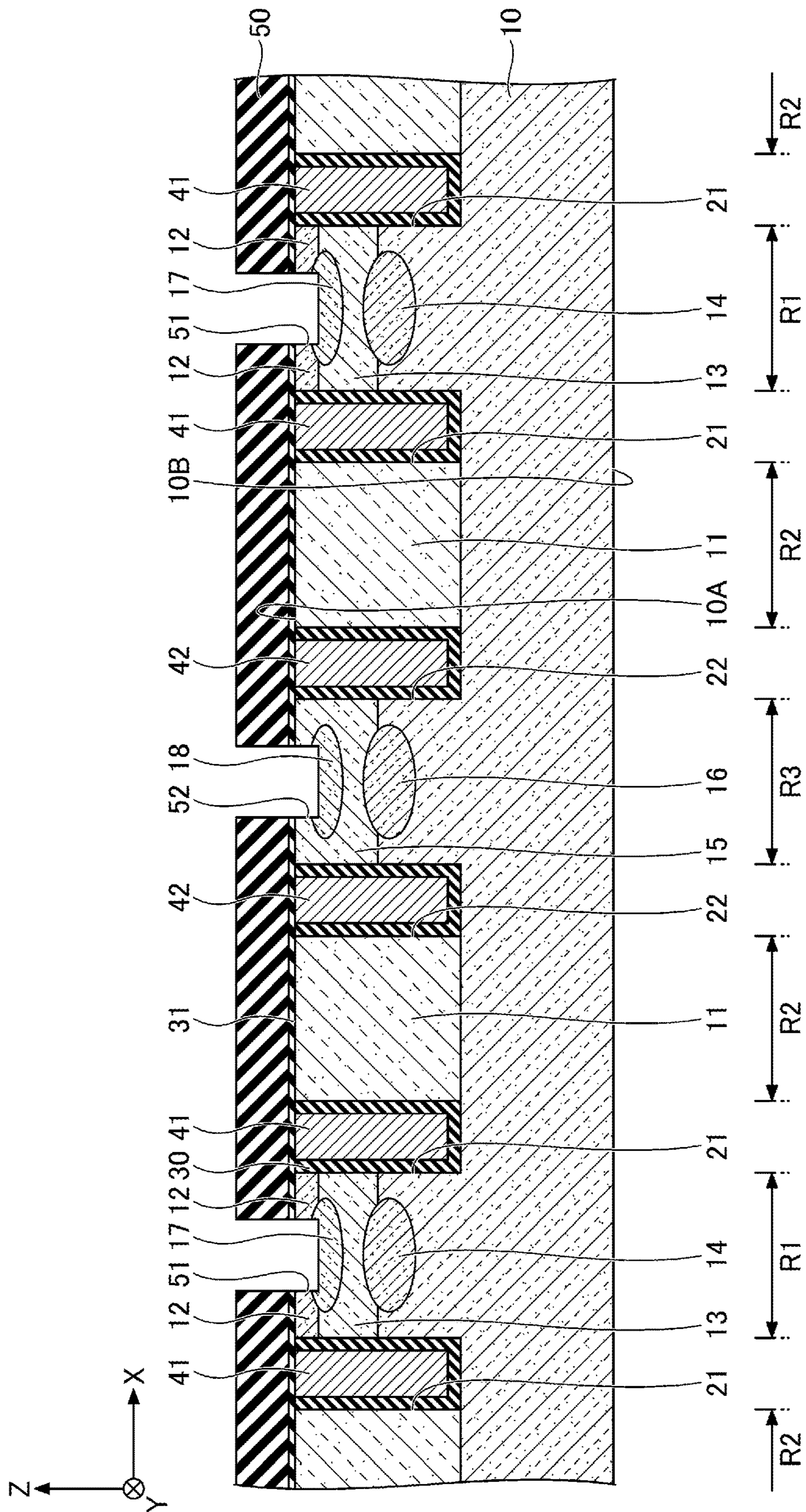


FIG.11

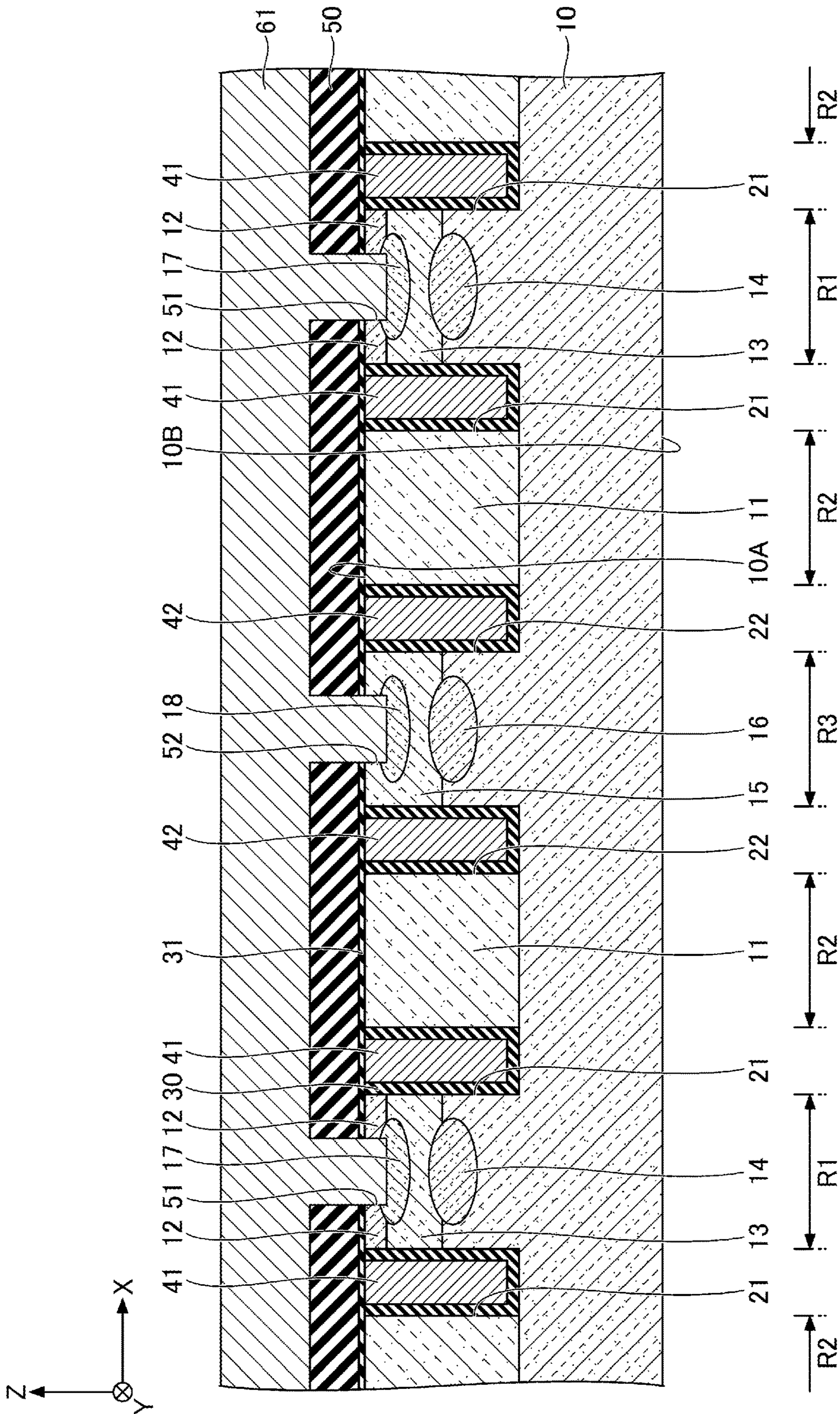


FIG.12

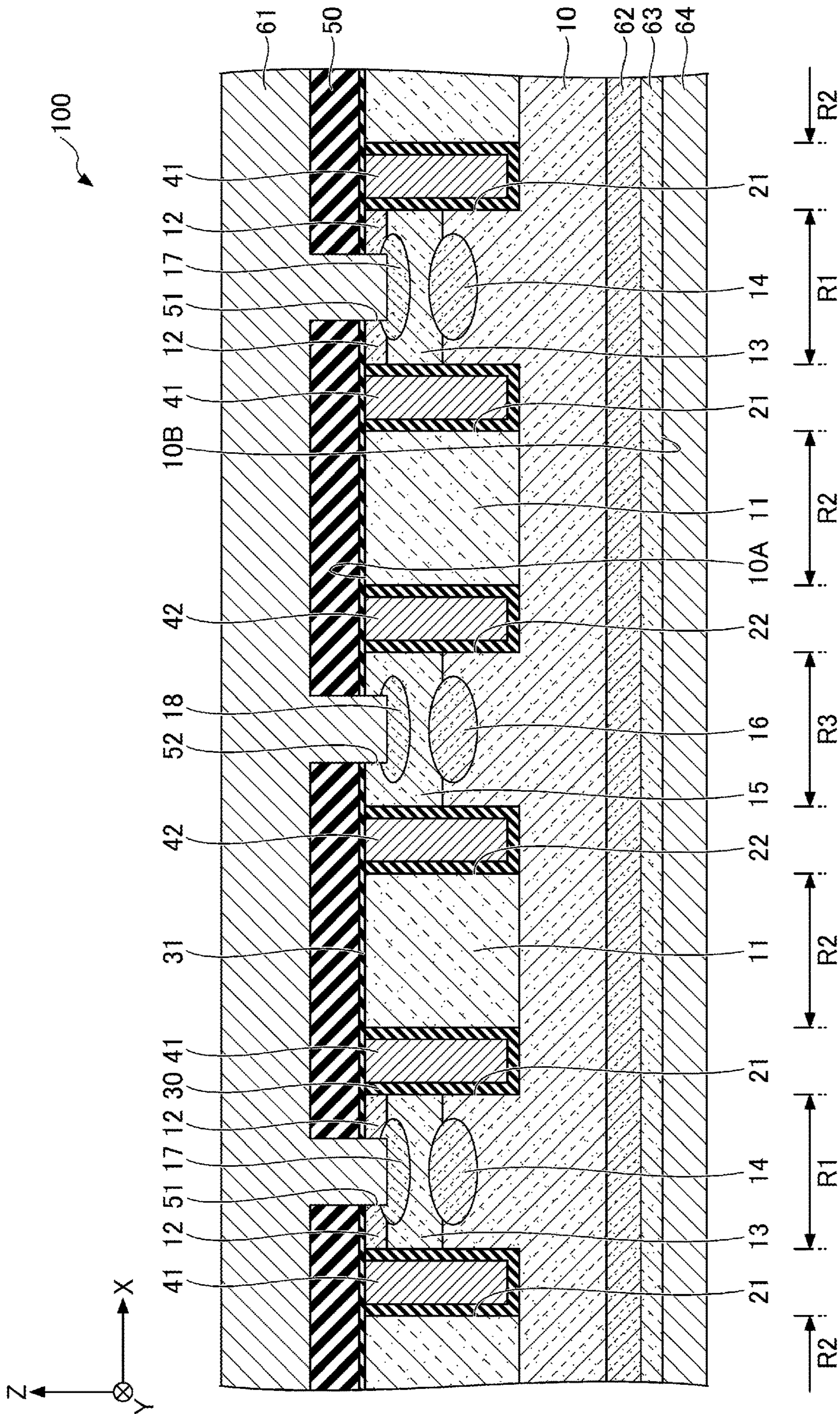


FIG.13

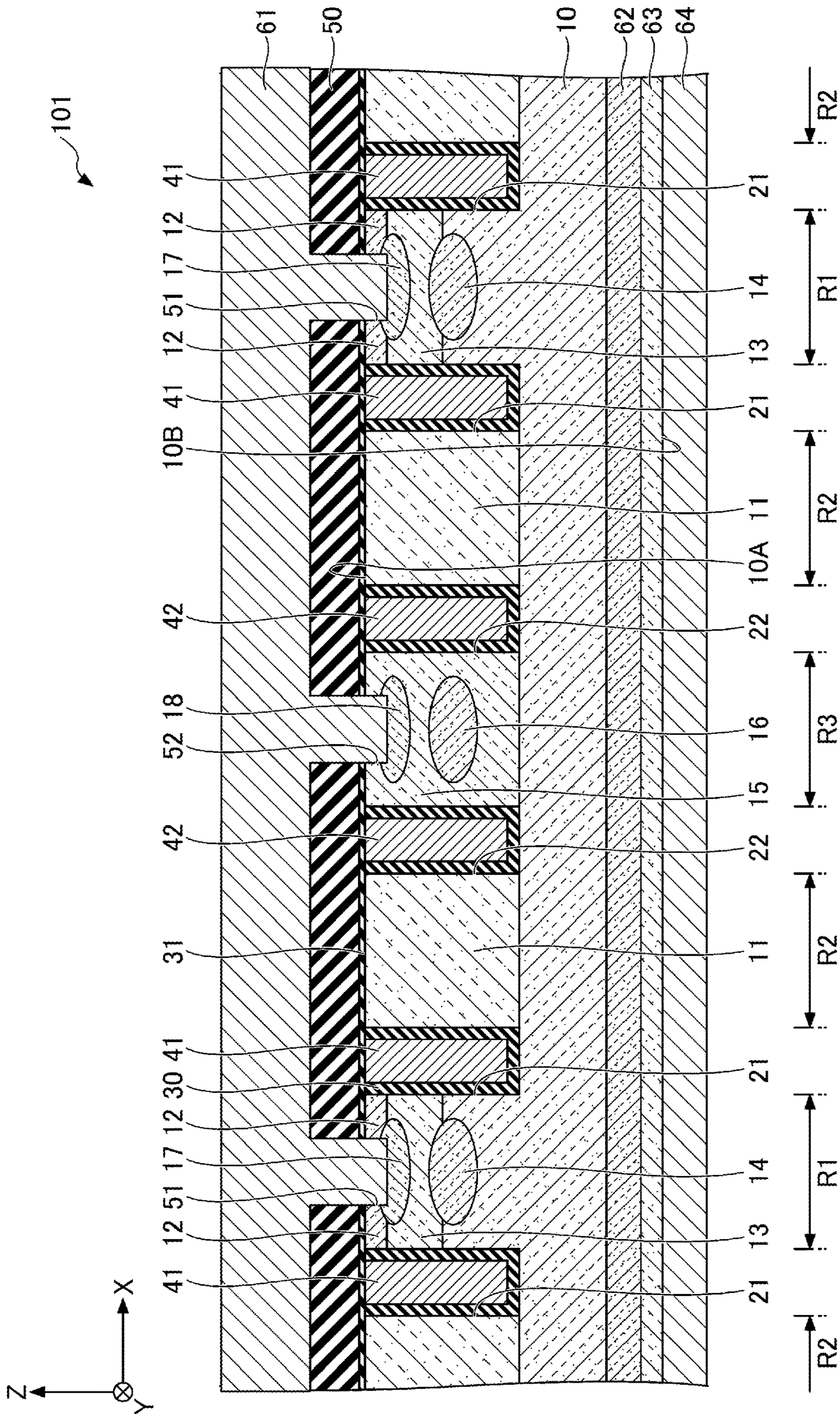


FIG.14

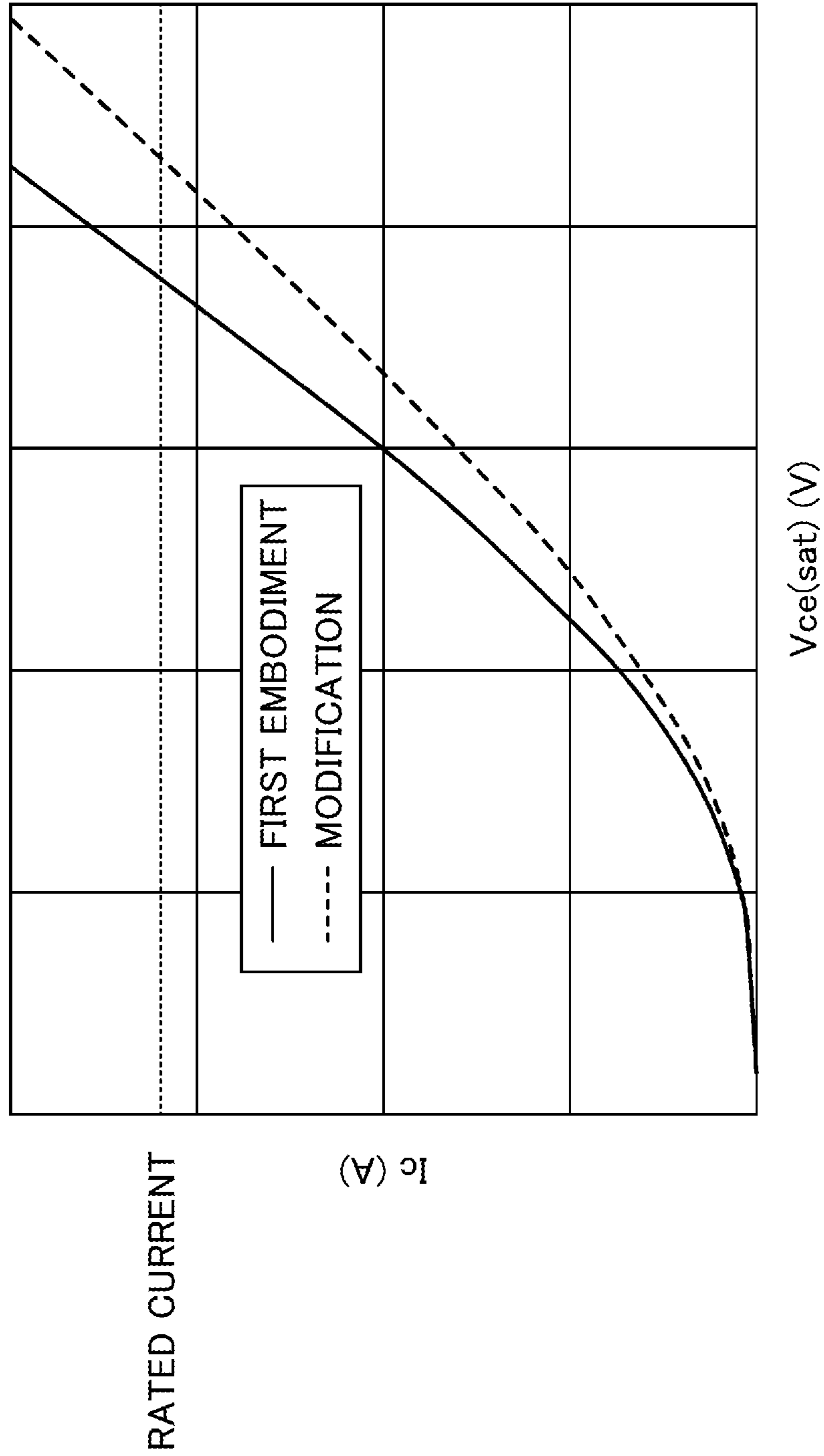


FIG. 15

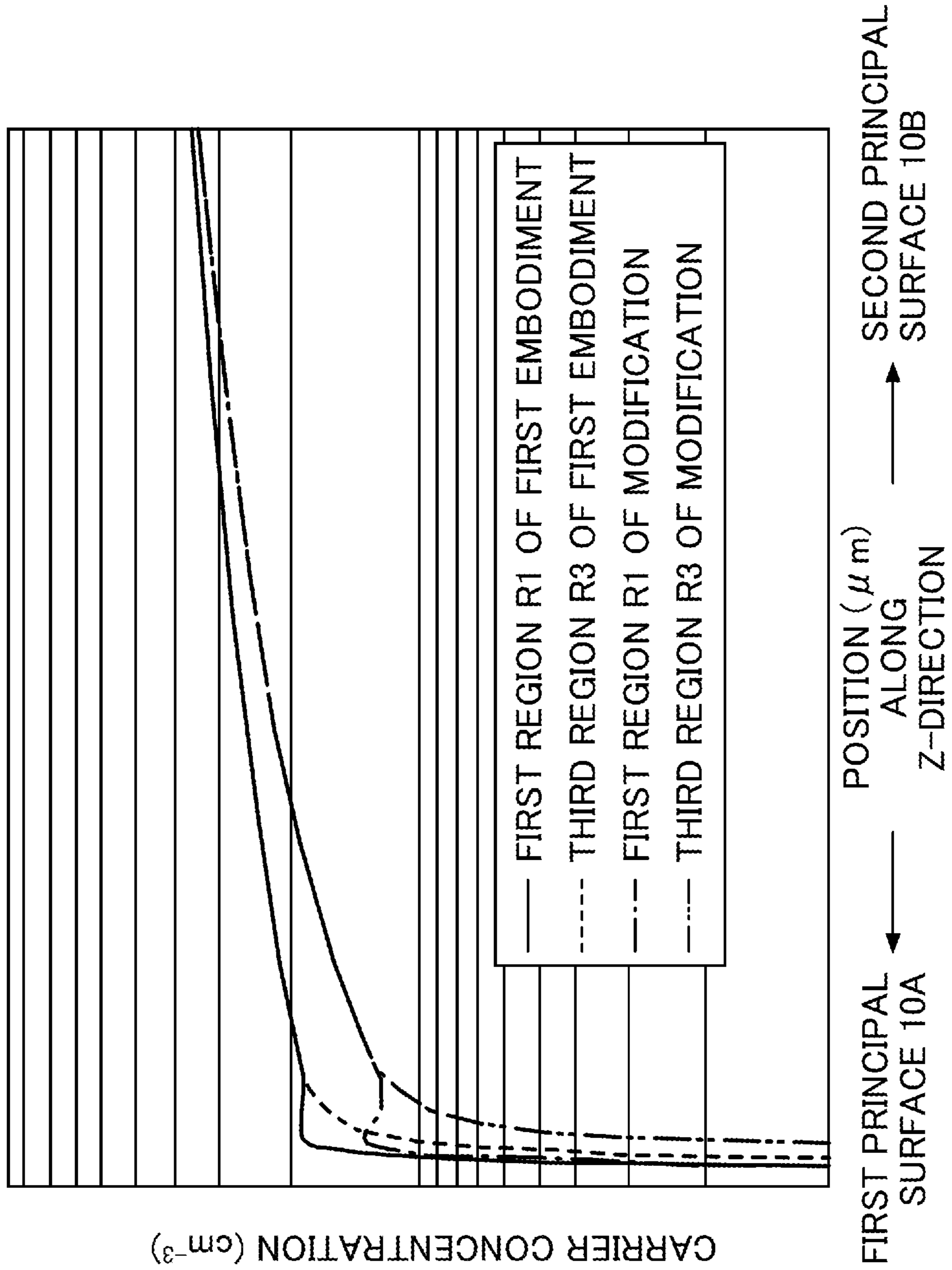
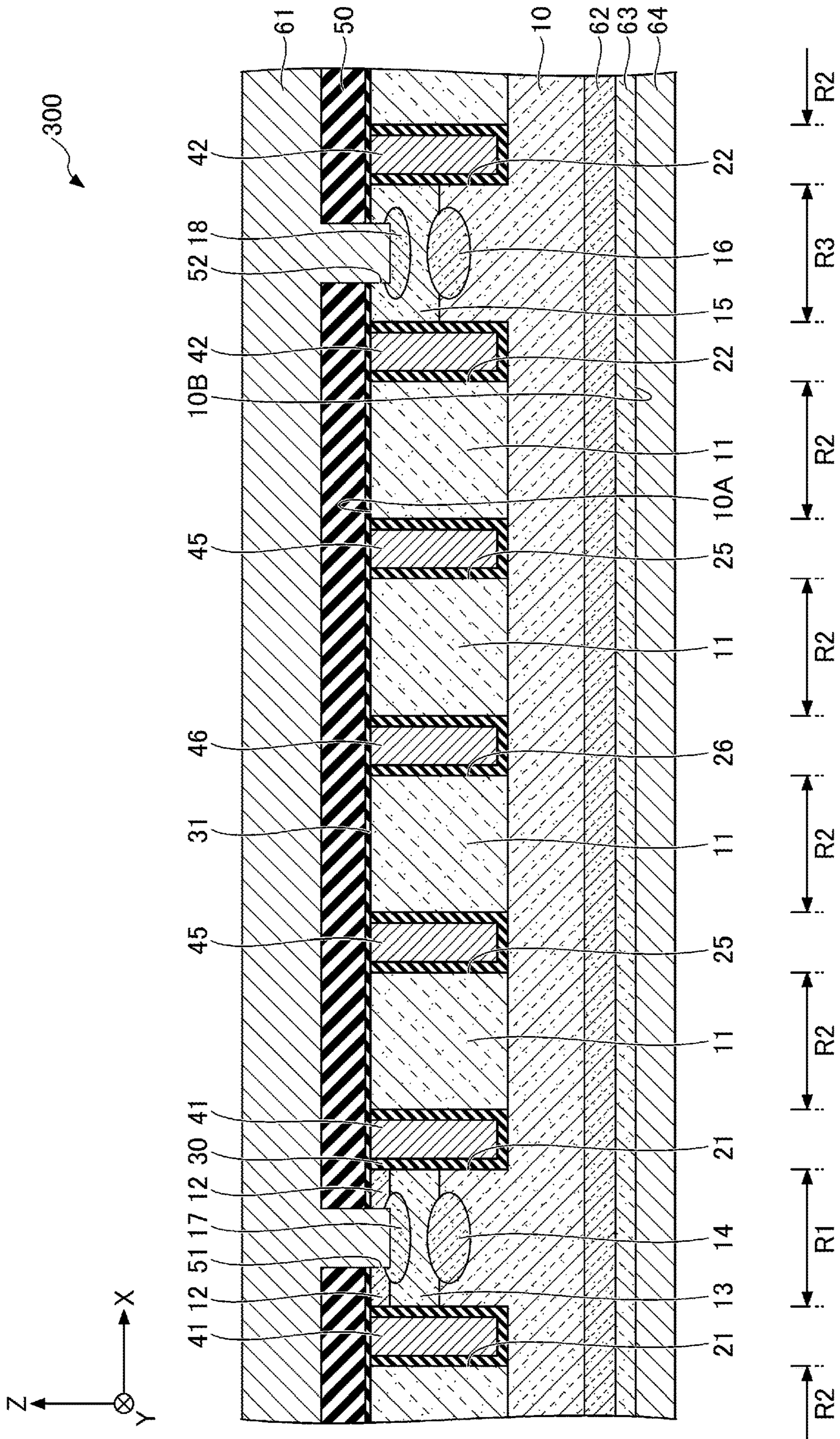


FIG.17



SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is based on and claims priority to Japanese Patent Application No. 2020-105121 filed on Jun. 18, 2020, the entire contents of which are incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present disclosure relates to semiconductor devices, and methods for manufacturing semiconductor devices.

2. Description of the Related Art

Among insulated gate bipolar transistors (IGBTs), there is a known semiconductor device provided with a high-concentration N-type semiconductor layer which is disposed under a P-type channel region and is in contact with the entire lower surface of the P-type channel region, such as that proposed in Japanese Laid-Open Patent Publication No. H08-316479 (now Japanese Patent No. 3288218), for example. A saturation voltage can be reduced by providing the high-concentration N-type semiconductor layer.

An example of a method for manufacturing the IGBT is proposed in Japanese Laid-Open Patent Publication No. 2008-205015 (now Japanese Patent No. 5089191), for example.

In conventional semiconductor devices having the high-concentration N-type semiconductor layer, characteristics, such as a threshold voltage or the like of a metal oxide semiconductor (MOS) structure of the IGBT, may easily vary.

SUMMARY OF THE INVENTION

One object of the present disclosure is to provide a semiconductor device, and a method for manufacturing the semiconductor device, which can easily adjust the saturation voltage, and reduce the variation in the characteristics.

According to one aspect of embodiments of the present disclosure, a semiconductor device includes a semiconductor substrate of a first conductivity type, having a first principal surface, and a second principal surface on an opposite side from the first principal surface; a first trench provided in the first principal surface; a second trench provided in the first principal surface; a first semiconductor layer of a second conductivity type, provided in the first principal surface between the first trench and the second trench; a second semiconductor layer of the first conductivity type, provided in the first principal surface at a position sandwiching the first trench between the second semiconductor layer and the first semiconductor layer, and making contact with the first trench; a third semiconductor layer of the second conductivity type, provided under the second semiconductor layer, and making contact with the second semiconductor layer and the first trench; a fourth semiconductor layer of the first conductivity type, provided under the third semiconductor layer, and making contact with the third semiconductor layer but separated from the first trench; a fifth semiconductor layer of the second conductivity type,

provided in the first principal surface at a position sandwiching the second trench between the fifth semiconductor layer and the first semiconductor layer; a first insulating film provided on an inner wall of the first trench; a first gate trench electrode provided inside the first trench via the first insulating film, and opposing the third semiconductor layer; a second insulating film provided on an inner wall of the second trench; a first emitter trench electrode provided inside the second trench via the second insulating film; a gate electrode connected to the first gate trench electrode; an emitter electrode connected to the first emitter trench electrode, the second semiconductor layer, the third semiconductor layer, and the fifth semiconductor layer; and a collector electrode provided in the second principal surface, wherein the first semiconductor layer is in an electrically floating state.

According to another aspect of the embodiments of the present disclosure, a method for manufacturing a semiconductor device, includes forming a first trench and a second trench in a first principal surface of a semiconductor substrate of a first conductivity type having the first principal surface and a second principal surface on an opposite side from the first principal surface; forming a first semiconductor layer of a second conductivity type in the first principal surface between the first trench and the second trench; forming a second semiconductor layer of the first conductivity type in the first principal surface, making contact with the first trench, at a position sandwiching the first trench between the second semiconductor layer and the first semiconductor layer; forming a third semiconductor layer of the second conductivity type under the second semiconductor layer, making contact with the second semiconductor layer and the first trench; forming a fourth semiconductor layer of the first conductivity type under the third semiconductor layer, making contact with the third semiconductor layer but separated from the first trench; forming a fifth semiconductor layer of the second conductivity type in the first principal surface at a position sandwiching the second trench between the fifth semiconductor layer and the first semiconductor layer; forming a first insulating film on an inner wall of the first trench; forming a first gate trench electrode inside the first trench via the first insulating film, and opposing the third semiconductor layer; forming a second insulating film on an inner wall of the second trench; forming a first emitter trench electrode inside the second trench via the second insulating film; forming a gate electrode connected to the first gate trench electrode; forming an emitter electrode connected to the first emitter trench electrode, the second semiconductor layer, the third semiconductor layer, and the fifth semiconductor layer; and forming a collector electrode in the second principal surface, wherein the first semiconductor layer is in an electrically floating state.

Other objects and further features of the present invention will be apparent from the following detailed description when read in conjunction with the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a diagram illustrating a layout of semiconductor layers and trench electrodes in a semiconductor device according to a first embodiment.

FIG. 2 is a cross sectional view illustrating the semiconductor device according to the first embodiment.

FIG. 3 is a cross sectional view (part 1) illustrating a method for manufacturing the semiconductor device according to the first embodiment.

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FIG. 4 is a cross sectional view (part 2) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 5 is a cross sectional view (part 3) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 6 is a cross sectional view (part 4) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 7 is a cross sectional view (part 5) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 8 is a cross sectional view (part 6) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 9 is a cross sectional view (part 7) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 10 is a cross sectional view (part 8) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 11 is a cross sectional view (part 9) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 12 is a cross sectional view (part 10) illustrating the method for manufacturing the semiconductor device according to the first embodiment.

FIG. 13 is a cross sectional view illustrating a semiconductor device according to a modification of the first embodiment.

FIG. 14 is a diagram illustrating a Vce-Ic characteristic.

FIG. 15 is a diagram illustrating simulation results related to carrier concentration.

FIG. 16 is a cross sectional view illustrating the semiconductor device according to a second embodiment.

FIG. 17 is a cross sectional view illustrating the semiconductor device according to a third embodiment.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

Embodiments of a semiconductor device, and a method for manufacturing the semiconductor device according to the present disclosure will be described, by referring to the drawings. In the drawings, those constituent elements having substantially the same functions and/or structure are designated by the same reference numerals, and a repeated description of substantially the same constituent elements may be omitted. In the following description, two directions, which are parallel to a surface of a substrate and are perpendicular to each other, are regarded as an X-direction and a Y-direction, and a direction perpendicular to the surface of the substrate is regarded as a Z-direction.

First Embodiment

A first embodiment will first be described. The first embodiment relates to a semiconductor device including an insulated gate bipolar transistor (IGBT). FIG. 1 is a diagram illustrating a layout of semiconductor layers and trench electrodes in the semiconductor device according to the first embodiment. FIG. 2 is a cross sectional view illustrating the semiconductor device according to the first embodiment. FIG. 2 corresponds to the cross sectional view along a line II-II in FIG. 1.

A semiconductor device 100 according to a first embodiment includes an N-type semiconductor substrate 10 having

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a first principal surface 10A, and a second principal surface 10B on an opposite side from the first principal surface 10A, as illustrated in FIG. 2. The semiconductor substrate 10 may be a silicon substrate, for example. A plurality of gate trenches 21, and a plurality of emitter trenches 22, are formed in the first principal surface 10A. The trenches 21 and 22 extend in the Y-direction, for example. Two trenches 21 form a pair, and two trenches 22 form a pair, for example, and the pair of trenches 21 and the pair of trenches 22 are alternately arranged in the X-direction. A distance between two trenches 21 that are adjacent to each other in the X-direction, a distance between two trenches 22 that are adjacent to each other in the X-direction, and a distance between the trenches 21 and 22 that are adjacent to each other in the X-direction, are the same. That is, if the trenches 21 and 22 are not distinguished from each other, the plurality of trenches are equally spaced in the X-direction and formed in a stripe shape in the first principal surface 10A. A first region R1 is defined between two trenches 21 that are adjacent to each other in the X-direction, a second region R2 is defined between the trench 21 and the trench 22 that are adjacent to each other in the X-direction, and a third region R3 is defined between two trenches 22 that are adjacent to each other in the X-direction. In the first embodiment, the first region R1 and the third region R3 are alternately disposed in the X-direction, with one second region R2 interposed between the first region R1 and the third region R3, such that the third region R3, the second region R2, the first region R1, the second region R2, the third region R3, the second region R2, the first region R1, . . . , are arranged in the X-direction.

In the first region R1, an N-type semiconductor layer 12 is provided in the first principal surface 10A. The N-type semiconductor layer 12 includes a higher concentration of N-type impurity than the semiconductor substrate 10. The N-type semiconductor layer 12 is exposed at the first principal surface 10A, and makes contact with the trench 21. A P-type semiconductor layer 13 is provided under the N-type semiconductor layer 12. The P-type semiconductor layer 13 makes contact with the N-type semiconductor layer 12 and the trench 21. In the Z-direction, a lower end of the P-type semiconductor layer 13 is located at a position above a lower end of the trench 21. A P-type semiconductor layer 17 is formed near an interface of the P-type semiconductor layer 13 with the N-type semiconductor layer 12. The P-type semiconductor layer 17 may be formed over a span of the N-type semiconductor layer 12 and the P-type semiconductor layer 13, or may be formed to include the interface between the N-type semiconductor layer 12 and the P-type semiconductor layer 13. The P-type semiconductor layer 17 is separated from the trench 21. The P-type semiconductor layer 17 includes a higher concentration of P-type impurity than the P-type semiconductor layer 13. In the Z-direction, a lower end of the P-type semiconductor layer 17 is located at a position above the lower end of the P-type semiconductor layer 13. An N-type semiconductor layer 14 is provided under the P-type semiconductor layer 13. The N-type semiconductor layer 14 includes a higher concentration of N-type impurity than the semiconductor substrate 10, but includes a lower concentration of N-type impurity than the N-type semiconductor layer 12. The N-type semiconductor layer 14 makes contact with the P-type semiconductor layer 13, and is separated from the trench 21.

In the second region R2, a P-type semiconductor layer 11 is provided in the first principal surface 10A. The P-type semiconductor layer 11 makes contact with the trench 21 and the trench 22. For example, in the Z-direction, a lower

end of the P-type semiconductor layer **11** is located at a position above the lower end of the trench **21**. For example, a depth of the P-type semiconductor layer **11** is greater than or equal to a depth of the trench **21**. The P-type semiconductor layer **11** includes a lower concentration of P-type impurity than the P-type semiconductor layer **13**.

In the third region **R3**, a P-type semiconductor layer **15** is provided in the first principal surface **10A**. For example, the P-type semiconductor layer **15** includes a concentration of P-type impurity approximately the same as the concentration of P-type impurity of the P-type semiconductor layer **13**. The P-type semiconductor layer **15** is exposed at the first principal surface **10A**, and makes contact with the trench **22**. For example, in the Z-direction, a lower end of the P-type semiconductor layer **15** may be located at the same position as the lower end of the P-type semiconductor layer **13**, or may be located at a position under the lower end of the P-type semiconductor layer **13**. For example, in the Z-direction, the lower end of the P-type semiconductor layer **15** may be located at the same position as the lower end of the P-type semiconductor layer **11**, or may be located at a position above the lower end of the P-type semiconductor layer **11**. A depth of the P-type semiconductor layer **15** may be equal to the depth of the P-type semiconductor layer **13**, or may be greater than the depth of the P-type semiconductor layer **13**, and less than or equal to the depth of the P-type semiconductor layer **11**. A P-type semiconductor layer **18** is formed inside the P-type semiconductor layer **15**. The P-type semiconductor layer **18** includes a higher concentration of P-type impurity than the P-type semiconductor layer **15**. For example, the P-type semiconductor layer **18** includes a concentration of P-type impurity approximately the same as the concentration of P-type impurity of the P-type semiconductor layer **17**. An N-type semiconductor layer **16** is provided under the P-type semiconductor layer **15**. The N-type semiconductor layer **16** includes a higher concentration of N-type impurity than the semiconductor substrate **10**. For example, the N-type semiconductor layer **16** includes a concentration of N-type impurity approximately the same as the concentration of N-type impurity of the N-type semiconductor layer **14**. At least a portion of the N-type semiconductor layer **16** overlaps the P-type semiconductor layer **15**, abuts the P-type semiconductor layer **15**, and is separated from the trench **22**.

An insulating film **30** is provided on inner walls of the trenches **21** and **22**. An insulating film **31** is provided on the first principal surface **10A**. That is, the insulating film **31** covers the P-type semiconductor layer **11** and the N-type semiconductor layer **12**. The insulating films **30** and **31** are thermal oxidation films, for example. Inside the trench **21**, a gate trench electrode **41** is provided via the insulating film **30**. The gate trench electrode **41** opposes the P-type semiconductor layer **13** via the insulating film **30**. Inside the trench **22**, an emitter trench electrode **42** is provided via the insulating film **30**. The gate trench electrode **41** and the emitter trench electrode **42** may be formed using polysilicon, for example. The insulating film **31** is also formed on the gate trench electrode **41** and the emitter trench electrode **42**.

A portion of the insulating film **30** inside the trench **21** functions as a gate insulator. In the first region **R1**, the N-type semiconductor layer **12**, the P-type semiconductor layer **13**, and the N-type semiconductor substrate **10** are aligned along the insulating film **30** inside the trench **21**, and the P-type semiconductor layer **13** functions as a channel region. That is, a metal oxide semiconductor (MOS) struc-

ture is formed by the first region **R1**, the insulating film **30**, and the gate trench electrode **41**.

An interlayer insulator **50** is provided on the insulating film **31**. The interlayer insulator **50** is a borophosphosilicate glass (BPSG) film, for example. Openings **51** reaching the P-type semiconductor layer **17** are formed in the interlayer insulator **50**, the insulating film **31**, and the N-type semiconductor layer **12**. The N-type semiconductor layer **12** is divided into two by the openings **51**. An opening **52** reaching the P-type semiconductor layer **18** is formed in the interlayer insulator **50**, the insulating film **31**, and the P-type semiconductor layer **15**. An emitter electrode (or emitter pad) **61** is provided on the interlayer insulator **50**. The emitter electrode **61** makes contact with the N-type semiconductor layer **12** and the P-type semiconductor layer **13**, through the openings **51**, and makes contact with the P-type semiconductor layers **15** and **18** through the opening **52**. The emitter electrode **61** may be formed using aluminum, for example.

A P-type semiconductor layer **63** is provided on the second principal surface **10B**, and an N-type semiconductor layer **62** is provided above the P-type semiconductor layer **63**. The N-type semiconductor layer **62** makes contact with the P-type semiconductor layer **63**. The N-type semiconductor layer **62** includes a higher concentration of N-type impurity than the semiconductor substrate **10**. A collector electrode **64** is provided on the second principal surface **10B**, that is, under the P-type semiconductor layer **63**. The collector electrode **64** makes contact with the P-type semiconductor layer **63**. The collector electrode **64** may be formed using laminated films of Al, Ti, Ni, and Au which are laminated in this order, downwardly from the P-type semiconductor layer **63**, for example. The collector electrode **64** may be formed of other materials, such as laminated films of Al, Ti, Ni, and Ag which are laminated in this order, downwardly from the P-type semiconductor layer **63**.

Each gate trench electrode **41** is drawn out and routed to a vicinity of an outer periphery of the semiconductor device **100**, for example, and is connected in common to a gate electrode (or gate pad), which is not illustrated. A shunt (resistor) may be provided between the gate trench electrode **41** and the gate electrode, as appropriate, so that the power supply delay time is uniform throughout the semiconductor device **100**. The gate electrode may be formed using aluminum, for example. Each emitter trench electrode **42** is drawn out and routed to a vicinity of the outer periphery of the perimeter of the semiconductor device **100**, for example, and is connected to the emitter electrode (or emitter pad) **61**.

The P-type semiconductor layer **11** is in an electrically floating state, because the P-type semiconductor layer **11** is not directly connected to the emitter electrode **61**, the collector electrode **64**, and the gate electrode.

Although not illustrated in the drawings, a so-called guard ring structure is provided on the outer periphery of the semiconductor device **100**, in order to maintain a certain withstand voltage (or voltage insulation).

Next, a method for manufacturing the semiconductor device **100** according to the first embodiment will be described. FIG. 3 through FIG. 12 are cross sectional views illustrating the method for manufacturing the semiconductor device **100** according to the first embodiment.

First, as illustrated in FIG. 3, the semiconductor substrate **10** having the first principal surface **10A**, and the second principal surface **10B**, is prepared, and the P-type semiconductor layer **11** is formed in the first principal surface **10A** in a region which becomes the second region **R2**, by ion implantation (or injection of ions) of the P-type impurity followed by a heat treatment.

Next, as illustrated in FIG. 4, the plurality of gate trenches **21** and the plurality of emitter trenches **22** are formed in the first principal surface **10A**. When forming the trenches **21** and the trenches **22**, a photoresist mask is formed on the first principal surface **10A**, and the semiconductor substrate **10** is etched using this photoresist mask, for example. The first region **R1** is defined between two trenches **21** that are adjacent to each other in the X-direction, the second region **R2** is defined between the trench **21** and the trench **22** that are adjacent to each other in the X-direction, and the third region **R3** is defined between two trenches **22** that are adjacent to each other in the X-direction.

Next, as illustrated in FIG. 5, the insulating film **30** is formed on the inner walls of the trenches **21** and **22**. The insulating film **30** is also formed on the first principal surface **10A**. The insulating film **30** may be formed thermal oxidation, for example.

Next, as illustrated in FIG. 6, the gate trench electrode **41** is formed inside the trench **21** via the insulating film **30**, and the emitter trench electrode **42** is formed inside the trench **22** via the insulating film **30**.

The P-type semiconductor layer **11** can be formed to a predetermined depth by heating during the formation of the insulating film **30**, or the like.

Next, as illustrated in FIG. 7, the portion of the insulating film **30** on the semiconductor substrate **10**, and the portion of the insulating film **30** on the P-type semiconductor layer **11**, are removed. That is, the insulating film **30** is removed from above an area where the P-type semiconductor layer **13** and the N-type semiconductor layer **12** are formed in the first region **R1**, an area where the P-type semiconductor layer **15** is formed in the third region **R3**, and an area where the P-type semiconductor layer **11** is formed in the second region **R2**. Then, the insulating film **31** to be implanted with ions is formed on the areas where the insulating film **30** was removed. The insulating film **31** to be implanted with ions is thinner than the insulating film **30**. The insulating film **31** may be formed by thermal oxidation, for example. The insulating film **31** is also formed on the gate trench electrode **41** and the emitter trench electrode **42**. Thereafter, the P-type semiconductor layer **13** is formed in the first region **R1**, and the P-type semiconductor layer **15** is formed in the third region **R3**, by ion implantation of the P-type impurity. The P-type semiconductor layer **13** and the P-type semiconductor layer **15** can be formed simultaneously. The P-type semiconductor layer **13** and the P-type semiconductor layer **15** may be formed in mutually different steps. Next, the N-type semiconductor layer **12** is formed in the first region **R1** by implanting the N-type impurity. The insulating film **31** protects the surface of the semiconductor substrate **10** and the P-type semiconductor layer **11** during the ion implantations described above.

Next, as illustrated in FIG. 8, the interlayer insulator **50** is formed on the insulating film **31**.

Next, as illustrated in FIG. 9, the openings **51** reaching the P-type semiconductor layer **13** are formed in the interlayer insulator **50**, the insulating film **31**, and the N-type semiconductor layer **12**, and the opening **52** reaching the P-type semiconductor layer **15** is formed in the interlayer insulator **50** and the insulating film **31**. The openings **51** and the opening **52** can be formed simultaneously. When forming the openings **51** and the opening **52**, a photoresist mask is formed on the interlayer insulator **50**, and the interlayer insulator **50**, the insulating film **31**, the N-type semiconductor layer **12**, and the P-type semiconductor layer **15** are etched using this photoresist mask. The opening **52** may

extend into the P-type semiconductor layer **15**. The openings **51** may extend into the P-type semiconductor layer **13**.

Next, as illustrated in FIG. 10, the N-type semiconductor layer **14** and the P-type semiconductor layer **17** in the first region **R1**, and the N-type semiconductor layer **16** and the P-type semiconductor layer **18** in the third region **R3**, are formed. When forming these semiconductor layers, the ion implantation of the N-type impurity for forming the N-type semiconductor layer **14** and the N-type semiconductor layer **16** are performed in the first region **R1** and the third region **R3**, respectively. Then, the ion implantation of the P-type impurity for forming the P-type semiconductor layer **17** and the P-type semiconductor layer **18** are performed in the first region **R1** and the third region **R3**, respectively. A heat treatment is performed after these ion implantations. Hence, the N-type semiconductor layer **14**, the N-type semiconductor layer **16**, the P-type semiconductor layer **17**, and the P-type semiconductor layer **18** can be formed in this manner. At least a portion of the N-type semiconductor layer **14** overlaps the P-type semiconductor layer **13**, and at least a portion of the N-type semiconductor layer **16** overlaps the P-type semiconductor layer **15**.

Next, as illustrated in FIG. 11, the emitter electrode **61** is formed on the interlayer insulator **50**. The emitter electrode **61** makes contact with the N-type semiconductor layer **12** and the P-type semiconductor layer **13** through the openings **51**, and makes contact with the P-type semiconductor layers **15** and **18** through the opening **52**.

Next, as illustrated in FIG. 12, the N-type semiconductor layer **62** is formed in the second principal surface **10B** by ion implantation of the N-type impurity. In addition, the P-type semiconductor layer **63** is formed in the second principal surface **10B** by ion implantation of the P-type impurity. Then, the collector electrode **64** is formed on the second principal surface **10B**.

Further, although not illustrated, the gate electrode, which connects to each gate trench electrode **41**, is formed.

For example, after forming the P-type semiconductor layer **17**, the P-type semiconductor layer **18**, the N-type semiconductor layer **14**, and the N-type semiconductor layer **16**, and before forming the emitter electrode **61**, an opening (not illustrated), which reaches the emitter trench electrode **42**, may be formed in the interlayer insulator **50** near the outer periphery of the semiconductor device **100**. The emitter electrode **61** can connect to the emitter trench electrode **42** through this opening.

Next, advantageous features or effects obtainable by the semiconductor device **100** according to the first embodiment will be described.

In the semiconductor device **100** according to the first embodiment, the N-type semiconductor layer **14** functions as a Hall barrier layer. In addition, the N-type semiconductor layer **14** is separated from the trench **21**. Accordingly, characteristics, such as a threshold voltage or the like of the MOS structure of the first region **R1**, is hardly affected by the N-type semiconductor layer **14**. That is, according to the first embodiment, it is possible to reduce the variation in the characteristics of the MOS structure.

The second region **R2** is provided adjacent to the first region **R1**, and the P-type semiconductor layer **11** in the electrically floating state is provided in the second region **R2**. For this reason, due to the effects of injection enhancement (IE), it is possible to obtain good static properties for the IGBT. In addition, the P-type semiconductor layer **11** and the P-type semiconductor layer **13** can be formed in separate steps, and for example, the P-type semiconductor layer **11** can be formed deeper than the P-type semiconductor layer

13. Accordingly, it is possible to obtain an excellent withstand voltage while obtaining good MOS characteristics in the first region R1.

The third region R3 is provided to sandwich the second region R2 between the first region R1 and the third region R3, and the trench 22 is provided between the second region R2 and the third region R3. In a case where the gate trench electrode 41 is provided inside the trench 22, an increase in a gate capacitance may deteriorate a short-circuit safe operation area (SCSOA) and switching characteristics. In the first embodiment, because the emitter trench electrode 42 connected to the emitter electrode 61 is provided inside the trench 22, it is possible to avoid deterioration of the characteristics caused by the increase in the gate, capacitance.

If the trenches 21 and 22 are not distinguished from each other, the plurality of trenches are equally spaced in the X-direction and formed in the stripe shape in the first principal surface 10A. For this reason, the density of the trenches is highly uniform, and it is possible to reduce the etching variation when forming the trenches. By reducing etching variation, a yield of the semiconductor device 100 can be improved, and further, it is possible to reduce the variation in electrical characteristics.

In the third region R3, the P-type semiconductor layer 15 connected to the emitter electrode 61 is provided to make contact with the N-type semiconductor substrate 10. For this reason, the carrier can be quickly discharged during the switching operation of the IGBT, and the switching characteristics can be improved.

Moreover, a saturation voltage $V_{ce(sat)}$ can be adjusted according to the depth of the P-type semiconductor layer 15. In the cross sectional view illustrated in FIG. 2, the depth of the P-type semiconductor layer 15 is equal to the depth of the P-type semiconductor layer 13, however, the depth of the P-type semiconductor layer 15 may be greater than the depth of the P-type semiconductor layer 13. FIG. 13 is a cross sectional view illustrating the semiconductor device according to a modification of the first embodiment.

In a semiconductor device 101 according to the modification of the first embodiment, the depth of the P-type semiconductor layer 15 is greater than the depth of the P-type semiconductor layer 13, and is less than or equal to the depth of the P-type semiconductor layer 11. The N-type semiconductor layer 16 is formed so that the entire N-type semiconductor layer 16 overlaps the P-type semiconductor layer 15. Other configurations of this modification are similar to those of the first embodiment.

When the semiconductor device 100 and the semiconductor device 101 are compared, the MOS characteristics are essentially the same, and the saturation voltage $V_{ce(sat)}$ of the semiconductor device 100 is lower than the saturation voltage $V_{ce(sat)}$ of the semiconductor device 101. FIG. 14 illustrates results of actual measurements made by the present inventors by making semiconductor devices according to the first embodiment and the modification thereof, and measuring a relationship (V_{ce} - I_c characteristic) between a collector-emitter voltage V_{ce} and a collector current I_c for each of the semiconductor devices according to the first embodiment and the modification thereof. As illustrated in FIG. 14, the threshold voltages of the first embodiment and the modification thereof are essentially the same. On the other hand, the collector-emitter voltage V_{ce} (saturation voltage $V_{ce(sat)}$) when a rated collector current I_c is applied is smaller for the first embodiment than for the modification thereof.

Results of simulation related to carrier concentration performed by the present inventors for the first embodiment

and the modification thereof are illustrated in FIG. 15. In this simulation, a hole concentration distribution in the Z-direction was calculated for a portion including the N-type semiconductor layer 14 in a plan view of the first region R1, and a portion including the N-type semiconductor layer 16 in a plan view of the third region R3. A solid line in FIG. 15 indicates the simulation result for the first region R1 of the first embodiment, a dashed line indicates the simulation result for the third region R3 of the first embodiment, a one-dot chain line indicates the simulation result for the first region R1 of the modification, and a two-dot chain line indicates the simulation result for the third region R3 of the modification.

As illustrated in FIG. 15, in the first embodiment, the simulation results obtained indicate a high hole concentration in both the first region R1 and the third region R3, when compared to the modification. It may be regarded that, because the P-type semiconductor layer 15 is formed to be shallower in the first embodiment when compared to the modification, a kind of carrier accumulation effect is obtained in the first embodiment, thereby resulting in the high hole concentration in both the first region R1 and the third region R3.

Accordingly, the saturation voltage $V_{ce(sat)}$ can be adjusted according to the depth of the P-type semiconductor layer 15, independently of the MOS characteristics. In a case where the depth of the P-type semiconductor layer 15 is equal to the depth of the P-type semiconductor layer 13, the P-type semiconductor layer 15 and the P-type semiconductor layer 13 can be formed simultaneously. On the other hand, by forming the P-type semiconductor layer 15 and the P-type semiconductor layer 13 in separate steps, the saturation voltage $V_{ce(sat)}$ can be adjusted while obtaining the desired MOS characteristics.

The N-type semiconductor layer 16 is preferably separated from the trench 22, because excellent effects of the IE can be obtained, and the saturation voltage $V_{ce(sat)}$ can further be reduced to improve the efficiency of the semiconductor device 100.

The depth of the P-type semiconductor layer 11 is preferably greater than or equal to the depth of the trench 21, because it becomes easier to relax the concentration of the electric field at the lower end of the trench 21.

Second Embodiment

Next, a second embodiment will be described. The second embodiment differs from the first embodiment, mainly in the arrangement of the first region R1, the second region R2, and the third region R3. FIG. 16 is a cross sectional view illustrating the semiconductor device according to the second embodiment.

In a semiconductor device 200 according to the second embodiment, a plurality of emitter trenches 25 are formed in the first principal surface 10A, in addition to the plurality of gate trenches 21 and the plurality of emitter trenches 22. The emitter trenches 25 extend in the Y-direction, for example. Similar to the first embodiment, the pair of trenches 21, and the pair of trenches 22, are alternately arranged in the X-direction. In addition, two trenches 25 are arranged between the pair of trenches 21 and the pair of trenches 22 that are adjacent to each other. The distance between two trenches 21 that are adjacent to each other in the X-direction, the distance between two trenches 22 that are adjacent to each other in the X-direction, a distance between two trenches 25 that are adjacent to each other in the X-direction, a distance between the trenches 21 and 25 that are adjacent

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to each other in the X-direction, and a distance between the trenches **22** and **25** that are adjacent to each other in the X-direction, are the same. That is, if the trenches **21**, **22**, and **25** are not distinguished from one another, the plurality of trenches are equally spaced in the X-direction and formed in a stripe shape in the first principal surface **10A**. Similar to the first embodiment, the first region **R1** is defined between two trenches **21** that are adjacent to each other in the X-direction, and the third region **R3** is defined between two trenches **22** that are adjacent to each other in the X-direction. The second region **R2** is defined between the trenches **21** and **25** that are adjacent to each other in the X-direction, between two trenches **25** that are adjacent to each other in the X-direction, and between the trenches **25** and **22** that are adjacent to each other in the X-direction. In the second embodiment, the first region **R1** and the third region **R3** are alternately disposed in the X-direction, with three second regions **R2** interposed between the first region **R1** and the third region **R3**, such that the third region **R3**, the three second regions **R2**, the first region **R1**, the three second regions **R2**, the third region **R3**, the three second regions **R2**, the first region **R1**, . . . , are arranged in the X-direction.

In the second region **R2**, the P-type semiconductor layer **11** is provided in the first principal surface **10A**. The P-type semiconductor layer **11** makes contact with two trenches (trenches **21** and **25**, or trenches **25**, or trenches **22** and **25**) that define the second region **R2** in the X-direction.

The insulating film **30** is also provided on the inner wall of trench **25**. An emitter trench electrode **45** is provided inside the trench **25** via the insulating film **30**. The emitter trench electrode **45** may be formed using polysilicon, for example. Similar to the emitter trench electrode **42**, the emitter trench electrode **45** is drawn out and routed to a vicinity of an outer periphery of the semiconductor device **200**, for example, and is connected to the emitter electrode (or emitter pad) **61**.

Other configurations of the second embodiment are similar to those of the first embodiment.

The second embodiment can also obtain the advantageous features or effects obtainable by the first embodiment. In addition, the effects of the IE can further be improved, and the saturation voltage $V_{ce(sat)}$ can further be reduced to improve the efficiency of the semiconductor device **200**.

The number of trenches **25** arranged between the pair of trenches **21** and the pair of trenches **22** that are adjacent to each other is not particularly limited, and the number of trenches **25** may be one or more, and three or more.

Third Embodiment

Next, a third embodiment will be described. The third embodiment differs from the second embodiment, mainly in the arrangement of the first region **R1**, the second region **R2**, and the third region **R3**. FIG. **17** is a cross sectional view illustrating the semiconductor device according to the third embodiment.

In a semiconductor device **300** according to the third embodiment, a plurality of gate trenches **26** are formed in the first principal surface **10A** in addition to the plurality of gate trenches **21**, the plurality of emitter trenches **22**, and the plurality of emitter trenches **25**. The trenches **26** extend in the Y-direction, for example. Similar to the second embodiment, the pair of trenches **21** and the pair of trenches **22** are alternately arranged in the X-direction. In addition, two trenches **25** are arranged between the pair of trenches **21** and the pair of trenches **22** that are adjacent to each other. Further, one trench **26** is arranged between the two trenches

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25 that are adjacent to each other. The distance between two trenches **21** adjacent to each other in the X-direction, the distance between two trenches **22** adjacent to each other in the X-direction, the distance between the trenches **21** and **25** adjacent to each other in the X-direction, a distance between the trenches **25** and **26** adjacent to each other in the X-direction, and the distance between the trenches **22** and **25** adjacent to each other in the X-direction, are the same. That is, if the trenches **21**, **22**, **25**, and **26** are not distinguished from one another, the plurality of trenches are equally spaced in the X-direction and formed in a stripe shape in the first principal surface **10A**. Similar to the second embodiment, the first region **R1** is defined between two trenches **21** adjacent to each other in the X-direction, and the third region **R3** is defined between two trenches **22** adjacent to each other in the X-direction. The second region **R2** is defined between the trenches **21** and **25** adjacent to each other in the X-direction, between two trenches **25** adjacent to each other in the X-direction, between the trenches **25** and **26** adjacent to each other in the X-direction, and between the trenches **26** and **22** adjacent to each other in the X-direction. In the third embodiment, the first region **R1** and the third region **R3** are alternately disposed in the X-direction, with four second regions **R2** interposed between the first region **R1** and the third region **R3**, such that the third region **R3**, the four second regions **R2**, the first region **R1**, the four second regions **R2**, the third region **R3**, the four second regions **R2**, the first region **R1**, . . . , are arranged in the X-direction.

In the second region **R2**, the P-type semiconductor layer **11** is provided in the first principal surface **10A**. The P-type semiconductor layer **11** makes contact with two trenches (trenches **21** and **25**, or trenches **25** and **26**, or trenches **22** and **25**) that define the second region **R2** in the X-direction.

The insulating film **30** is also provided on the inner wall of trench **26**. A gate trench electrode **46** is provided inside the trench **26** via the insulating film **30**. The gate trench electrode **46** may be formed using polysilicon, for example. Similar to the gate trench electrode **41**, the gate trench electrode **46** is drawn out and routed to a vicinity of an outer periphery of the semiconductor device **300**, for example, and is connected to the gate electrode (or gate pad), which is not illustrated.

Other configurations of the third embodiment are similar to those of the second embodiment.

The third embodiment can also obtain the advantageous features or effects obtainable by the second embodiment. In addition, the input capacitance can be increased while avoiding the increase of the gate capacitance in the MOS structure affecting the properties of the IGBT. Hence, the gate noise can be reduced.

According to each of the embodiments of the present disclosure, it is possible to easily adjust the saturation voltage, and reduce the variation in the characteristics.

Although the embodiments are numbered with, for example, "first," "second," and "third," the ordinal numbers do not imply priorities of the embodiments.

Further, the present invention is not limited to these embodiments, but various variations, modifications, and substitutions of a part or all of the embodiments may be made without departing from the scope of the present invention.

What is claimed is:

1. A semiconductor device comprising:
 - a semiconductor substrate of a first conductivity type, having a first principal surface, and a second principal surface on an opposite side from the first principal surface;

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a first trench provided in the first principal surface;
 a second trench provided in the first principal surface;
 a third trench provided in the first principal surface;
 a fourth trench provided in the first principal surface;
 a first semiconductor layer of a second conductivity type, 5
 provided in the first principal surface between the first
 trench and the second trench;
 a second semiconductor layer of the first conductivity
 type, provided in the first principal surface at a position
 sandwiching the first trench between the second semi- 10
 conductor layer and the first semiconductor layer, and
 making contact with the first trench;
 a third semiconductor layer of the second conductivity
 type, provided under the second semiconductor layer,
 and making contact with the second semiconductor layer 15
 and the first trench;
 a fourth semiconductor layer of the first conductivity type,
 provided under the third semiconductor layer, and
 making contact with the third semiconductor layer but
 separated from the first trench; 20
 a fifth semiconductor layer of the second conductivity
 type, provided in the first principal surface at a position
 sandwiching the second trench between the fifth semi-
 conductor layer and the first semiconductor layer;
 a sixth semiconductor layer of the first conductivity type 25
 provided on the third semiconductor layer, making
 contact with the third semiconductor layer and the third
 trench, separated from the second semiconductor layer,
 and connected to the emitter electrode;
 a first insulating film provided on an inner wall of the first 30
 trench;
 a first gate trench electrode provided inside the first trench
 via the first insulating film, and opposing the third
 semiconductor layer;
 a second insulating film provided on an inner wall of the 35
 second trench;
 a first emitter trench electrode provided inside the second
 trench via the second insulating film;
 a third insulating film provided on an inner wall of the 40
 third trench;
 a second gate trench electrode provided inside the third
 trench via the third insulating film, opposing the third
 semiconductor layer, and connected to the gate elec-
 trode;
 a fourth insulating film provided on an inner wall of the 45
 fourth trench;
 a second emitter trench electrode provided inside the
 fourth trench via the fourth insulating film, and con-
 nected to the emitter electrode;
 a gate electrode connected to the first gate trench elec- 50
 trode;
 an emitter electrode connected to the first emitter trench
 electrode, the second semiconductor layer, the third
 semiconductor layer, and the fifth semiconductor layer;
 and 55
 a collector electrode provided in the second principal
 surface, wherein
 the first semiconductor layer is in an electrically floating
 state,
 the first trench is arranged between the second trench and 60
 the third trench,
 the second trench is arranged between the first trench and
 the fourth trench,
 the third semiconductor layer makes contact with the third
 trench,
 the fourth semiconductor layer is separated from the third
 trench,

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the fifth semiconductor layer makes contact with the
 fourth trench, and
 the third trench, the first trench, the second trench, and the
 fourth trench are equally spaced and formed in a stripe
 shape along a predetermined direction.
 2. The semiconductor device as claimed in claim 1,
 further comprising:
 a seventh semiconductor layer of the first conductivity
 type, provided under the fifth semiconductor layer, and
 making contact with the fifth semiconductor layer.
 3. The semiconductor device as claimed in claim 2,
 wherein the seventh semiconductor layer is separated from
 the second trench.
 4. The semiconductor device as claimed in claim 1,
 wherein a depth of the first semiconductor layer is greater
 than or equal to a depth of the first trench.
 5. The semiconductor device as claimed in claim 1,
 wherein a depth of the fifth semiconductor layer is equal to
 a depth of the third semiconductor layer.
 6. The semiconductor device as claimed in claim 1,
 wherein a depth of the fifth semiconductor layer is greater
 than a depth of the third semiconductor layer, and is less than
 or equal to a depth of the first semiconductor layer.
 7. The semiconductor device as claimed in claim 1,
 further comprising:
 a fifth trench provided in the first principal surface at a
 position between the first trench and the second trench;
 a fifth insulating film provided on an inner wall of the fifth
 trench;
 a third emitter trench electrode provided inside the fifth
 trench via the fifth insulating film, and connected to the
 emitter electrode, wherein
 the first semiconductor layer is provided between the first
 trench and the fifth trench that are adjacent to each
 other, and between the second trench and the fifth
 trench that are adjacent to each other, and
 the first trench, the fifth trench, and the second trench are
 equally spaced and formed in a stripe shape along the
 predetermined direction.
 8. The semiconductor device as claimed in claim 7,
 wherein
 a plurality of fifth trenches are provided in the first
 principal surface between the first trench and the sec-
 ond trench,
 the fifth insulating film and the third emitter trench
 electrode are provided for each of the plurality of fifth
 trenches,
 the first semiconductor layer is provided between two fifth
 trenches that are adjacent to each other, and
 the first trench, the plurality of fifth trenches, and the
 second trench are equally spaced and formed in a stripe
 shape along the predetermined direction.
 9. The semiconductor device as claimed in claim 8,
 further comprising:
 a sixth trench provided in the first principal surface
 between two fifth trenches that are adjacent to each
 other;
 a sixth insulating film provided on an inner wall of the
 sixth trench; and
 a third gate trench electrode provided inside the sixth
 trench via the sixth insulating film, and connected to the
 gate electrode, wherein
 the first semiconductor layer is provided between the fifth
 trench and the sixth trench that are adjacent to each
 other, and

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the plurality of fifth trenches, and the sixth trench are equally spaced and formed in a stripe shape along the predetermined direction.

10. A method for manufacturing a semiconductor device, comprising:

forming a first trench, a second trench, a third trench, and a fourth trench in a first principal surface of a semiconductor substrate of a first conductivity type having the first principal surface and a second principal surface on an opposite side from the first principal surface;

forming a first semiconductor layer of a second conductivity type in the first principal surface between the first trench and the second trench;

forming a second semiconductor layer of the first conductivity type in the first principal surface, making contact with the first trench, at a position sandwiching the first trench between the second semiconductor layer and the first semiconductor layer;

forming a third semiconductor layer of the second conductivity type under the second semiconductor layer, making contact with the second semiconductor layer and the first trench;

forming a fourth semiconductor layer of the first conductivity type under the third semiconductor layer, making contact with the third semiconductor layer but separated from the first trench;

forming a fifth semiconductor layer of the second conductivity type in the first principal surface at a position sandwiching the second trench between the fifth semiconductor layer and the first semiconductor layer;

forming a sixth semiconductor layer of the first conductivity type provided on the third semiconductor layer, making contact with the third semiconductor layer and the third trench, separated from the second semiconductor layer, and connected to the emitter electrode;

forming a first insulating film on an inner wall of the first trench;

forming a first gate trench electrode inside the first trench via the first insulating film, and opposing the third semiconductor layer;

forming a second insulating film on an inner wall of the second trench;

forming a first emitter trench electrode inside the second trench via the second insulating film;

forming a third insulating film on an inner wall of the third trench;

forming a second gate trench electrode inside the third trench via the third insulating film, opposing the third semiconductor layer, and connected to the gate electrode;

forming a fourth insulating film on an inner wall of the fourth trench;

forming a second emitter trench electrode inside the fourth trench via the fourth insulating film, and connected to the emitter electrode;

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forming a gate electrode connected to the first gate trench electrode;

forming an emitter electrode connected to the first emitter trench electrode, the second semiconductor layer, the third semiconductor layer, and the fifth semiconductor layer; and

forming a collector electrode in the second principal surface, wherein

the first semiconductor layer is in an electrically floating state,

the first trench is arranged between the second trench and the third trench,

the second trench is arranged between the first trench and the fourth trench,

the third semiconductor layer makes contact with the third trench,

the fourth semiconductor layer is separated from the third trench,

the fifth semiconductor layer makes contact with the fourth trench, and

the third trench, the first trench, the second trench, and the fourth trench are equally spaced and formed in a stripe shape along a predetermined direction.

11. The method for manufacturing the semiconductor device as claimed in claim **10**, further comprising:

forming an insulating film on the second semiconductor layer and the fifth semiconductor layer, before forming the emitter electrode;

forming a first opening, reaching the third semiconductor layer, in the insulating film and the second semiconductor layer; and

forming a second opening, reaching the fifth semiconductor layer, in the insulating film,

wherein the emitter electrode is connected to the second semiconductor layer and the third semiconductor layer through the first opening, and is connected to the fifth semiconductor layer through the second opening.

12. The method for manufacturing the semiconductor device as claimed in claim **11**, wherein the forming the fourth semiconductor layer includes ion implantation of an impurity of the first conductivity type through the first opening.

13. The method for manufacturing the semiconductor device as claimed in claim **12**, wherein ion implantation of the impurity of the first conductivity type forms a seventh semiconductor layer of the first conductivity type having at least a portion thereof overlapping the fifth semiconductor layer.

14. The method for manufacturing the semiconductor device as claimed in claim **13**, wherein the seventh semiconductor layer is separated from the second trench.

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